神钢集团的端子、连接器用镀锡铜合金板条
KOBE STEEL's Tin Plating Copper Alloy Strips for Terminals and Connectors.

镀锡种类 Tin Plating Types		特征 Characteristic	镀层组成 Plating Compositions		性能 Performance			
			Ni 基底镀层 Ni under Plating	Sn镀层 Tin Plating	降低插入力 Reduction of Insertion Force 摩擦系数 Frictional Properties	高温可靠性 Heat Reliability 接触电阻 Contact Resistance	焊锡浸湿性 Solder Wet-ability	耐微滑动磨损性 Fretting Characteristics
新回流镀锡 **New Reflow Tin Plating**	**标准** **Standard**	低插入力 Lower Insertion Force	**无** **Non**	**0.6～1.3μm**	◎ **Excellent** **Less 50% than Reflow tin plating**	○～△ **Good**	△ **a little Good**	○ **Better**
	类型 S **Type S**	低插入力 Lower Insertion Force 高温可靠性 Better Heat Reliability	**0.1～0.8μm**	**0.6～1.3μm**	◎ **Excellent** **Less 50% than Reflow tin plating**	◎ **Excellent**	△ **a little Good**	○ **Better**
	PCB端子用 类型S **Type S for Printed Circuit Board connector**	低插入力 Lower Insertion Force 焊锡浸湿性 Better Solder Wet-ability	**0.1～0.8μm**	**0.6～1.3μm**	○ **Better** **Less 25% than Reflow tin plating**	◎ **Excellent**	○ **Better**	-
TN电镀 **TN Plating**		低插入力 Lower Insertion Force	**0.1～0.8μm**	**0.4～0.8μm**	○ **Better** **Less 25% than Reflow tin plating**	◎ **Excellent**	△ **a little Good**	○～△ **Good**
TQ电镀 **TQ Plating**		高温可靠性 Better Heat Reliability 焊锡浸湿性 Better Solder Wet-ability	**0.1～0.8μm**	**1.0～2.0μm**	-	◎ **Excellent**	○ **Better**	○～△ **Good**
回流镀锡 **Reflow Tin Plating**			**无** **Non**	**0.8～2.0μm**	× **inferior**	○ **Better**	○ **Better**	○～△ **Good**
电气光泽电镀 **Electrical Brightness Tin Plating**			**无** **Non**	**0.8～2.0μm**	△ **a little Good** **Less 15% than Reflow tin plating**	○ **Better**	△ **a little Good**	○～△ **Good**